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# Preface

Dear Distinguished Authors and Guests,

The Organizing Committee warmly welcomes you to 2016 The International Conference on Nanomaterial, Semiconductor and Composite Materials (ICNSCM2016), held on June 18-19, 2016 in Singapore.

The aim of ICNSCM2016 is to present the latest research and results of scientists (professors, students, PhD Students, engineers, and post-doc scientist) related to Nanomaterial, Semiconductor and Composite Materials. This conference provides opportunities for the different areas delegates to exchange new ideas and application experiences face to face, to establish business or research relations and to find global partners for future collaboration.

The conference program is extremely rich, featuring high-impact presentation. We hope that the conference results constituted significant contribution to the knowledge in these up to date scientific field.

The proceeding records the fully refereed papers presented at the conference. The main conference themes and tracks are mechanical structures and smart materials and other correlation technique. Hopefully, all participants and other interested readers benefit scientifically from the proceedings and also find it stimulating in the process.

Finally we wish all the authors and attendees of ICNSCM2016 a unique, rewarding and enjoyable memory at ICNSCM2016 in Singapore. We look forward to your participation in the 2<sup>nd</sup> ICNSCM in 2017.

With our warmest regards,

Editor of ICNSCM2016